

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









3.0x1.0 mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Part Number: APECVA3010EC

High Efficiency Red

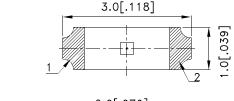
Features

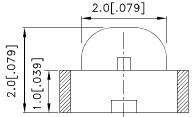
- 3.0mmx1.0mm SMT LED, 2.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for back light and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

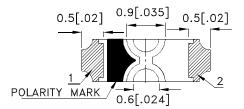
Description

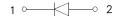
The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

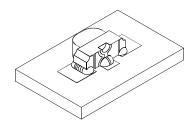
Package Dimensions











- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAJ1855 **REV NO: V.1 DATE: MAR/19/2009** PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: S.P.Chen ERP: 1203009115

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		21	Min.	Тур.	201/2
APECVA3010EC	High Efficiency Red (GaAsP/GaP)	WATER CLEAR	4	15	120°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	V _F =0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I=20mA
lr	Reverse Current	High Efficiency Red		10	uA	V _R =5V

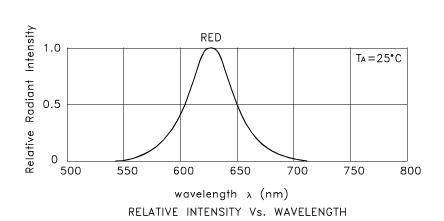
- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

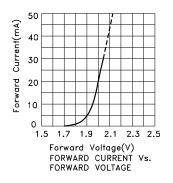
<u> </u>						
High Efficiency Red						
75	mW					
30	mA					
160	mA					
5	V					
-40°C To +85°C						
-40°C To +85°C						
	High Efficiency Red 75 30 160 5 -40°C To +85°C					

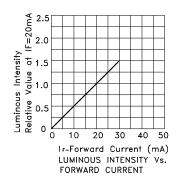
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

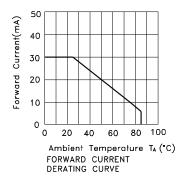
SPEC NO: DSAJ1855 **REV NO: V.1** DATE: MAR/19/2009 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: S.P.Chen ERP: 1203009115

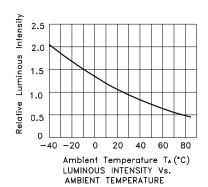


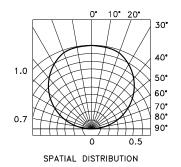
High Efficiency Red APECVA3010EC











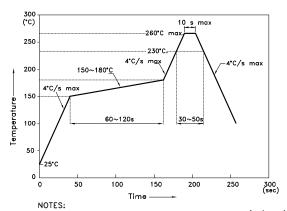
 SPEC NO: DSAJ1855
 REV NO: V.1
 DATE: MAR/19/2009
 PAGE: 3 OF 5

 APPROVED: WYNEC
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APECVA3010EC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

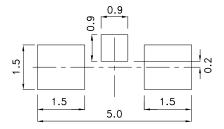
Reflow Soldering Profile For Lead-free SMT Process.



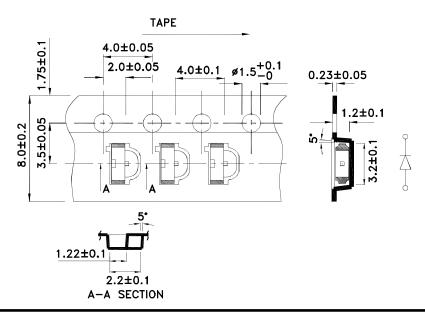
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

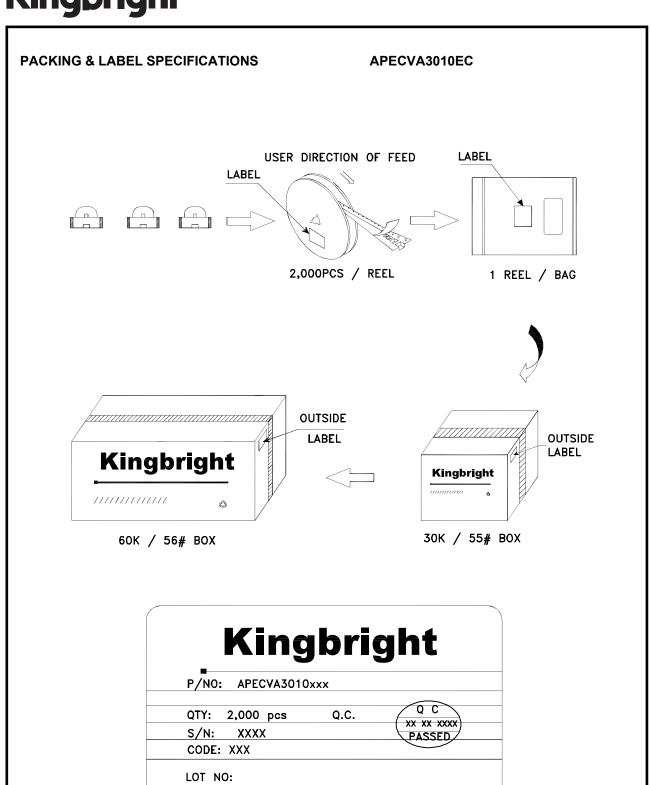
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)



SPEC NO: DSAJ1855 **REV NO: V.1 DATE: MAR/19/2009** PAGE: 4 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: S.P.Chen ERP: 1203009115



SPEC NO: DSAJ1855 APPROVED: WYNEC REV NO: V.1 CHECKED: Allen Liu DATE: MAR/19/2009 DRAWN: S.P.Chen

RoHS Compliant

PAGE: 5 OF 5 ERP: 1203009115